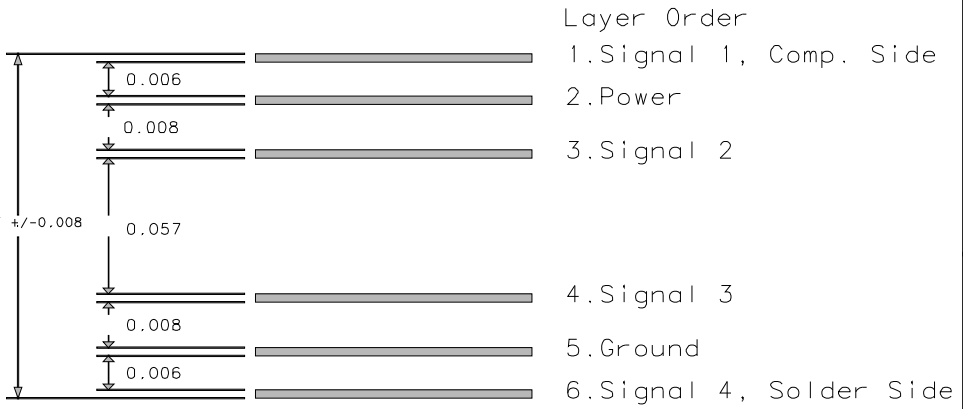


BOARD'S DRILL SCHEDULE

SYMBOL	FHS	COUNT	PLATED	Tolerance	COMMENT
○	.018	272	YES	+ .000/- .004	
⊞	.02	4165	YES	+ .000/- .004	
⊘	.0236	378	YES	+/- 0.05mm	Note 12.
⊞	.028	503	YES	---	
⊙	.0315	2	YES	---	
⊞	.033	40	YES	---	
⊕	.041	443	YES	---	
□	.047	1	NO	---	
	.04725	2	YES	---	
	.057	13	YES	---	
	.106	4	YES	---	
	.106	13	NO	---	
	.113	6	NO	---	
	.152	8	YES	---	



Board Characteristics :

- All dimensions are given in inches unless specified otherwise.
- Material FR4 - Tg > 170C.
- Minimum trace width 0.007" on all layers.
- Minimum Clearance 0.006" on all layers.
- 1 oz copper for all Trace and Power Layers.
- Apply ENTEC or equivalent Organic Coating over bare copper.
Apply Solder Mask over bare copper.
- Board Thickness: 0.093 +/- 0.008".
- Mill the Top and Bottom of board on the solder side to a thickness of 0.062" +/- 0.008".
- Silkscreen on Component and Solder Sides.
- 45 degree chamfer.
- Hole diameter tolerances : +/- 0.002" unless specified otherwise.
- Interlayer spacing: as specified.
- This is a pressfit technology through hole with the following specs
 - 12-1. Finished hole size: 0.6mm +/- 0.05mm
 - 12-2. Drilled hole size: 0.7mm +/- 0.02mm
 - 12-3. Thickness of through hole plating: min 25 μm Cu
 - 12-4. Inside through hole: OSP with 0.12 - 0.15 μm.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES .XXX DO NOT SCALE DRAWING	CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP		
	APPROVALS	DATE	TITLE		
	DRAWN M. Bogdan	6/9/99	CDF L1 CrateSum Board Specification Drawing		
	CHECKED H. Sanders	6/9/99	SIZE B	FSCM NO.	DWG. NO. B - 2330
ISSUED		SCALE 1/4		REV. B	
SIMILAR TO	ACT. WT	CALC. WT		SHEET 1 of 1	